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an opening in said covering structure, the opening sized and positioned to expose a portion of the first face, including said electrical connection region, and configured to admit a lead extending in a direction substantially parallel to the first face, to contact the electrical connection region: and

a heat dissipation region, in direct contact with said second face.

2. The electronic device of Claim 1, wherein said heat dissipation region and said second face of said body have equal area.

3. The electronic device of Claim 1, wherein said heat dissipation region is of metal, preferably of copper.

4. (Amended) The electronic device according to claim 1, wherein said heat dissipation region has a thickness of 50 to 200 μm .

5. The electronic device according to claim 1, wherein said covering structure comprises a passivation region and a protective region of a polymer material.

6. The electronic device of Claim 5, wherein said polymer material comprises polyimide.

7. The electronic device of Claim 5, wherein said polymer material comprises "SU8".

8. The electronic device according to claim 5, wherein said protective region is opaque.

9. The electronic device according to claim 5, wherein said protective region has a thickness of 20 to 70 μm .

Please add new claims 27-33 as follows:

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27. (New) The device of claim 1, further comprising a metallic lead affixed at a first end to the electrical connection region and extending from the connection region in a direction substantially parallel to the first face.

28. (New) The device of claim 27 wherein a surface area of the portion of the metallic lead in contact with the electrical connection region and affixed thereto is less than the surface area of the portion of the first face.

29. (New) The device of claim 27 wherein a second end of the metallic lead is affixed to a flexible strip.

30. (New) The device of claim 27 wherein a second end of the metallic lead is affixed to a contact pad on a ceramic base.

31. (New) An electronic device, comprising:
a body of semiconductor material having a first and a second face;
an electrical connection region formed on a periphery of said first face;
a covering structure, covering said first face and having a face transverse to the first face;

an opening in said covering structure, the opening sized and positioned to expose a portion of the first face, including said electrical connection region, and configured to admit a lead extending from a direction transverse to the transverse face of the covering structure, to contact the electrical connection region; and

a heat dissipation region, in direct contact with said second face.

32. (New) An electronic device, comprising:
a body of semiconductor material having first and second faces substantially opposite each other and a third face lying in a plane transverse to the first and second faces;